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US 6507530 B1	20030114 7	Weighted throttling mechanism with rank 3
		based throttling for a memory system

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# Development of a thermal management solution for a ruggedized Pentium based notebook computer

Rujano, J.R.; Cardenas, R.; Rahman, M.M.; Moreno, W.A.; Thermal and Thermomechanical Phenomena in Electronic Systems, 1998. ITHERM '98. The Sixth Intersociety Conference on , 27-30 May 1998 Pages:8 - 14

[Abstract] [PDF Full-Text (820 KB)] IEEE CNF

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2, 26-30 Oct. 1997

Pages: 7.3 - 31-7.3-36 vol. 2

[Abstract] [PDF Full-Text (468 KB)] IEEE CNI

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Manufacturing Technology, IEEE Transactions on], Volume: 21, Issue: 2, May 1998

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4 Exceptional performance from the development, qualification and implementation of a silicone adhesive for bonding heatsinks to semiconductor packages

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